TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π-MOSⅤ)

2SK2545

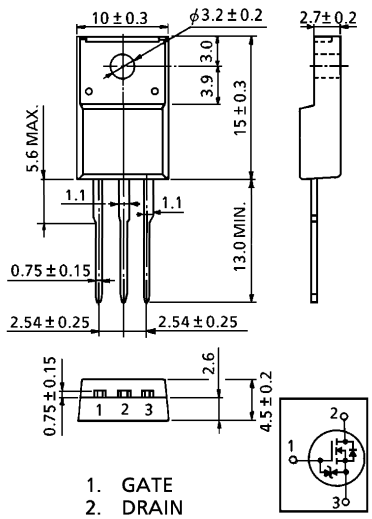
HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

INDUSTRIAL APPLICATIONS

- Low Drain-Source ON Resistance : $R_{DS\,(ON)} = 0.9\Omega$ (Typ.)
- High Forward Transfer Admittance : $|Y_{fs}| = 5.5S$ (Typ.)
- Low Leakage Current : $I_{DSS} = 100\mu A$ (Max.) ($V_{DS} = 600V$)
- Enhancement-Mode : $V_{th} = 2.0 \sim 4.0V$ ($V_{DS} = 10V$, $I_D = 1mA$)

Unit in mm



JEDEC	—
EIAJ	SC-67
TOSHIBA	2-10R1B

Weight : 1.9g

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		V_{DSS}	600	V
Drain-Gate Voltage ($R_{GS} = 20k\Omega$)		V_{DGR}	600	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	DC	I_D	6	A
	Pulse	I_{DP}	24	A
Drain Power Dissipation (Tc = 25°C)		P_D	40	W
Single Pulse Avalanche Energy**		E_{AS}	345	mJ
Avalanche Current		I_{AR}	6	A
Repetitive Avalanche Energy*		E_{AR}	4	mJ
Channel Temperature		T_{ch}	150	°C
Storage Temperature Range		T_{stg}	−55~150	°C

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th\,(ch\text{-}c)}$	3.125	°C / W
Thermal Resistance, Channel to Ambient	$R_{th\,(ch\text{-}a)}$	62.5	°C / W

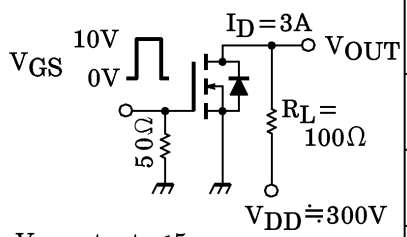
Note ;

* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

** $V_{DD} = 90V$, $T_{ch} = 25°C$ (initial), $L = 16.8mH$, $R_G = 25\Omega$, $I_{AR} = 6A$

This transistor is an electrostatic sensitive device.
Please handle with caution.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

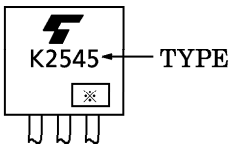
CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I_{GSS}	$V_{GS}=\pm25V$, $V_{DS}=0V$	—	—	±10	μA
Gate-Source Breakdown Voltage		$V_{(BR)\,GSS}$	$I_G=\pm10\mu A$, $V_{DS}=0V$	±30	—	—	V
Drain Cut-off Current		I_{DSS}	$V_{DS}=600V$, $V_{GS}=0V$	—	—	100	μA
Drain-Source Breakdown Voltage		$V_{(BR)\,DSS}$	$I_D=10mA$, $V_{GS}=0V$	600	—	—	V
Gate Threshold Voltage		V_{th}	$V_{DS}=10V$, $I_D=1mA$	2.0	—	4.0	V
Drain-Source ON Resistance		$R_{DS\,(ON)}$	$V_{GS}=10V$, $I_D=3A$	—	0.9	1.25	Ω
Forward Transfer Admittance		$\|Y_{fs}\|$	$V_{DS}=10V$, $I_D=3A$	2.0	5.5	—	S
Input Capacitance		C_{iss}	$V_{DS}=10V$, $V_{GS}=0V$, f=1MHz	—	1300	—	pF
Reverse Transfer Capacitance		C_{rss}		—	130	—	
Output Capacitance		C_{oss}		—	400	—	
Switching Time	Rise Time	t_r		—	25	—	ns
	Turn-on Time	t_{on}		—	45	—	
	Fall Time	t_f		—	40	—	
	Turn-off Time	t_{off}		—	150	—	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Q_g	$V_{DD}\fallingdotseq400V$, $V_{GS}=10V$, $I_D=6A$	—	30	—	nC
Gate-Source Charge		Q_{gs}		—	18	—	
Gate-Drain ("Miller") Charge		Q_{gd}		—	12	—	

V_{IN} : t_r, $t_f<5ns$,
Duty ≦ 1%, $t_w=10\mu s$

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I_{DR}	—	—	—	6	A
Pulse Drain Reverse Current	I_{DRP}	—	—	—	24	A
Diode Forward Voltage	V_{DSF}	$I_{DR}=6A$, $V_{GS}=0V$	—	—	−1.7	V
Reverse Recovery Time	t_{rr}	$I_{DR}=6A$, $V_{GS}=0V$	—	1000	—	ns
Reverse Recovery Charge	Q_{rr}	$dI_{DR}/dt=100A/\mu s$	—	7.0	—	μC

MARKING

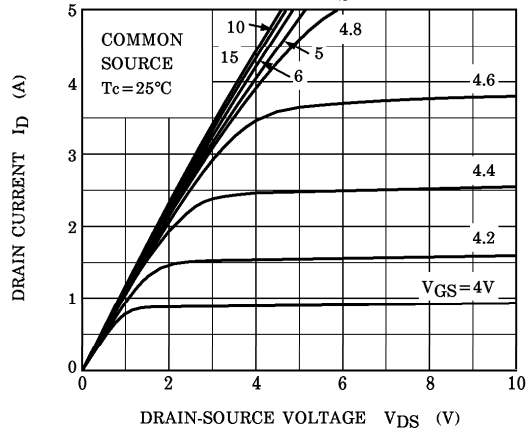


※ Lot Number

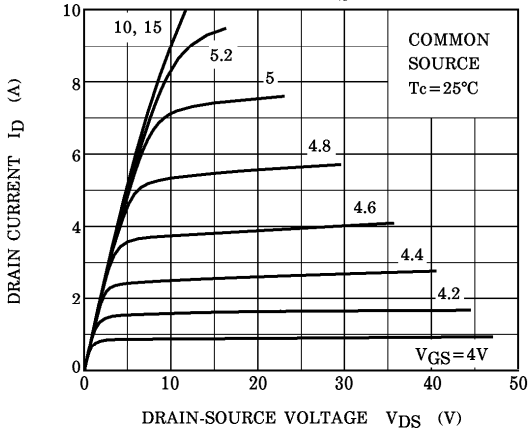
□□ — Month (Starting from Alphabet A)

Year (Last Number of the Christian Era)

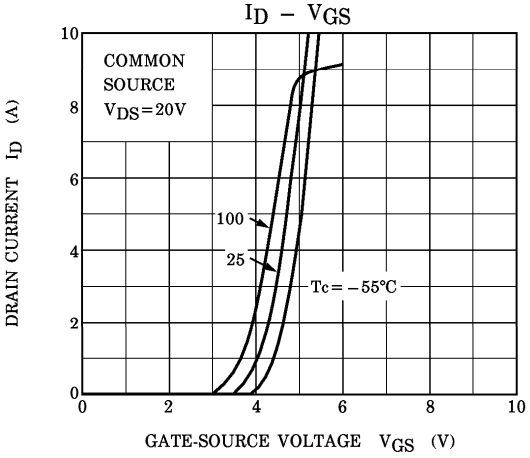
I_D – V_{DS}



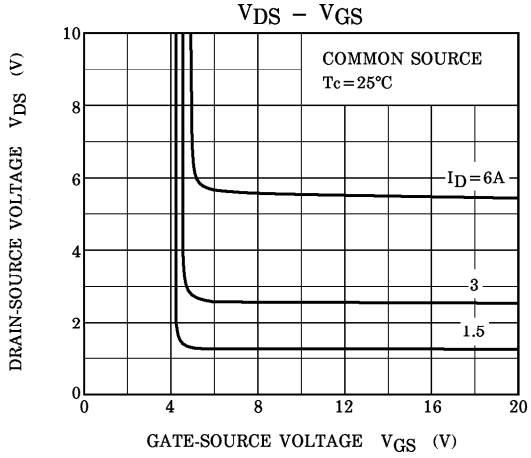
I_D – V_{DS}



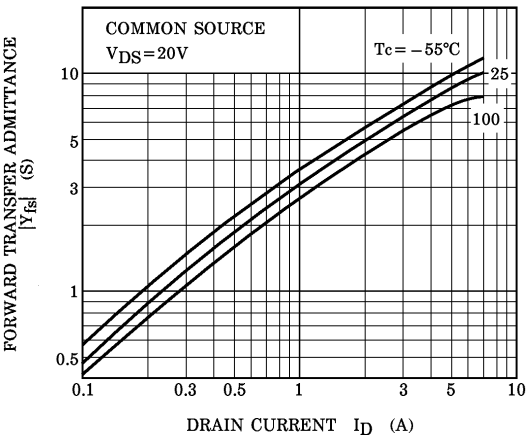
I_D – V_{GS}



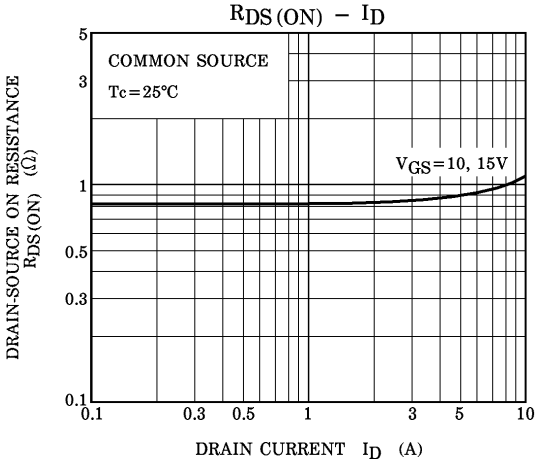
V_{DS} – V_{GS}



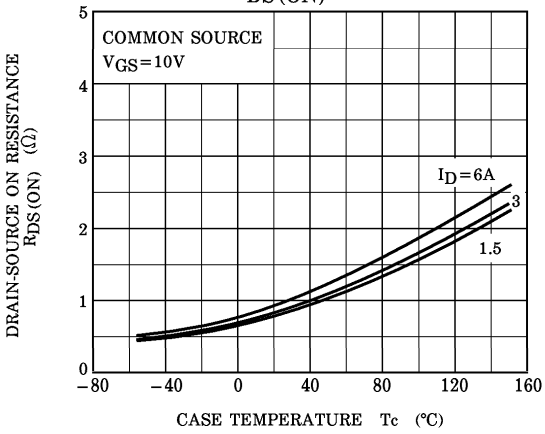
$|Y_{fs}|$ – I_D



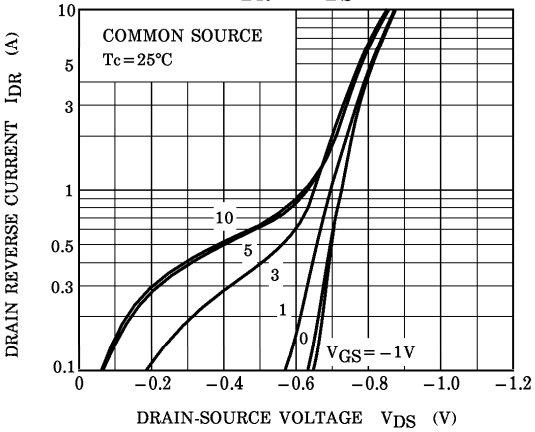
$R_{DS\,(ON)}$ – I_D



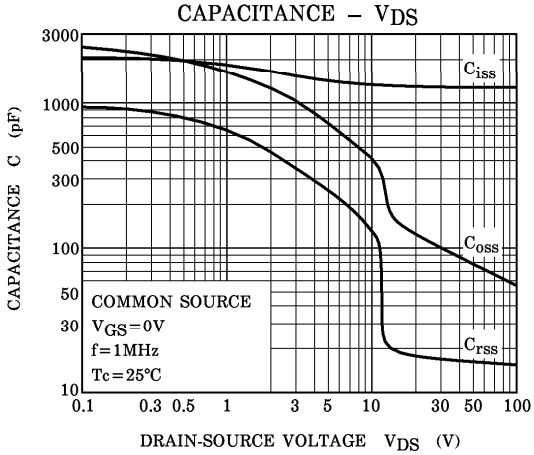
$R_{DS(ON)}$ – Tc



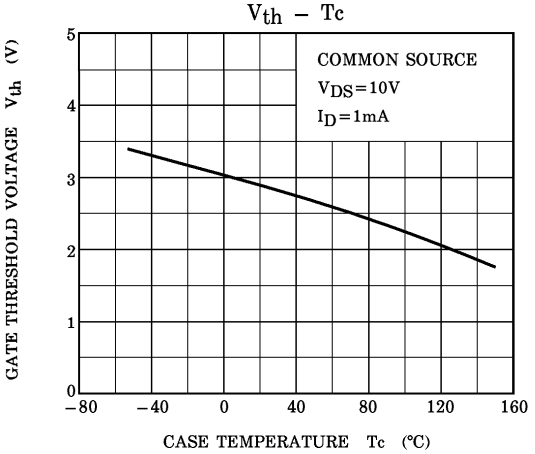
I_{DR} – V_{DS}



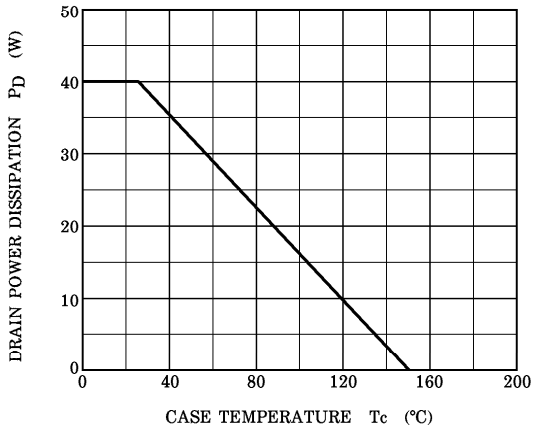
CAPACITANCE – V_{DS}



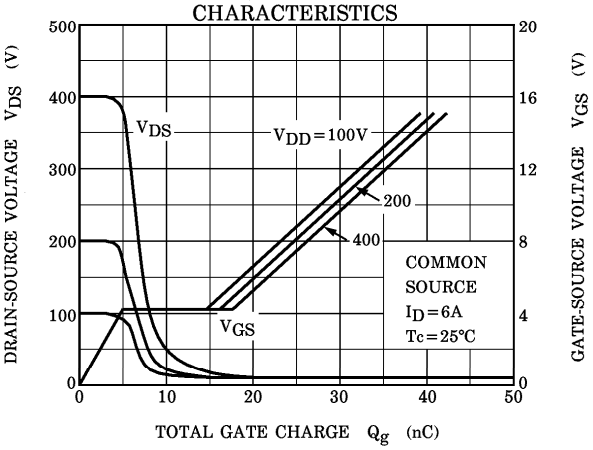
V_{th} – Tc



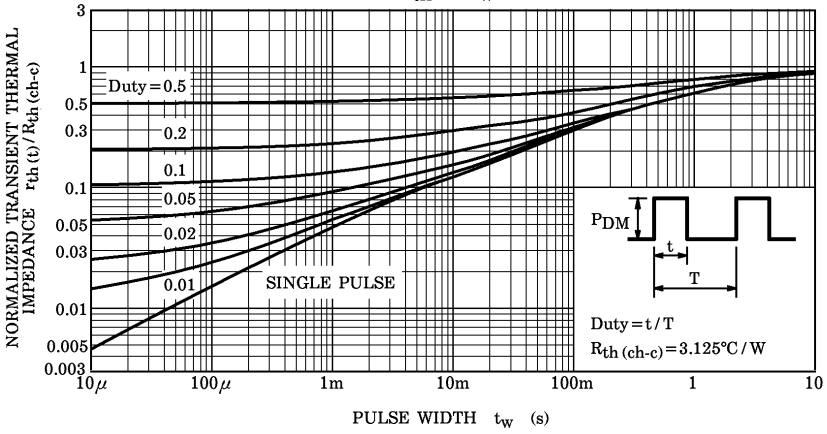
P_D – Tc



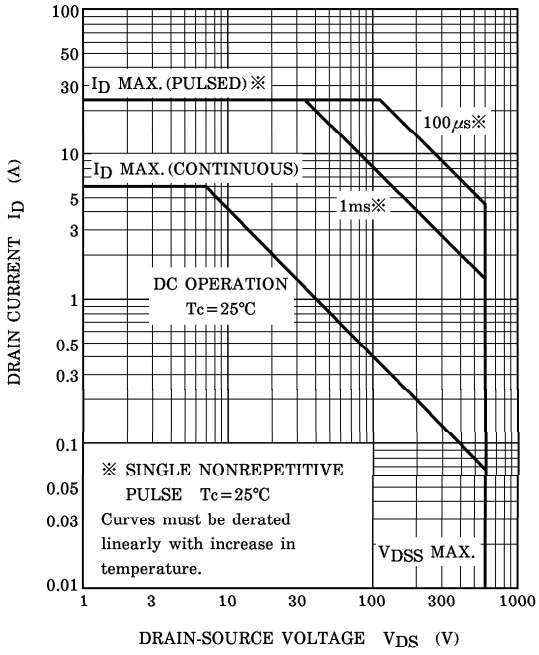
DYNAMIC INPUT / OUTPUT CHARACTERISTICS



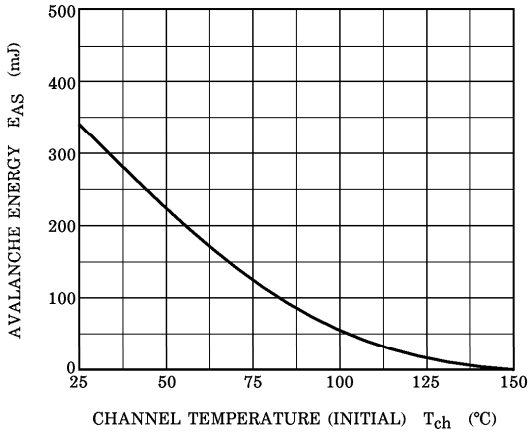
r_{th} – t_w

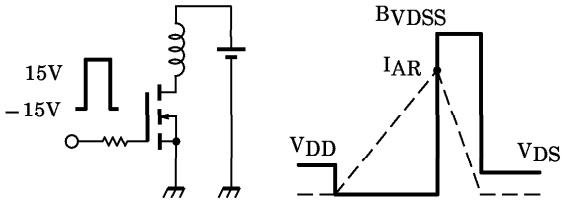


SAFE OPERATING AREA



E_{AS} – T_{ch}





TEST CIRCUIT WAVE FORM

Peak I_{AR} = 6A, R_G = 25Ω
V_{DD} = 90V, L = 16.8mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$